

FEATURES

- Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.
- Available as non-RoHS (Sn/Pb plating), standard, and as RoHS by adding "-PBF" suffix.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150	°C
Thermal Resistance Junction To Case	$R_{\theta JC}$	5.0	°C/W
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C ⁽¹⁾	P_D	0.8 25	W mW/°C
Drain Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current @ $T_C = +25^\circ\text{C}$ ⁽²⁾	I_{D1}	8.0	A
Drain Current @ $T_C = +100^\circ\text{C}$ ⁽²⁾	I_{D2}	5.0	A
Off State Current(Peak Total Value) ⁽³⁾	I_{DM}	32	A(pk)
Source Current	I_S	8.0	A

Note 1: Derate linearly 0.2W/°C for $T_C > +25^\circ\text{C}$

Note 2: The following formula derives the maximum theoretic I_D limit. I_D is also limited by package and internal wires and may be limited due to pin diameter.

$$I_D = \frac{V_{Tj(max)} - T_C}{R_{\theta JC} \times R_{DS(on)} @ T_{j(max)}}$$

Note 3: $I_{DM} = 4 \times I_{D1}$ as calculated in Note 2

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

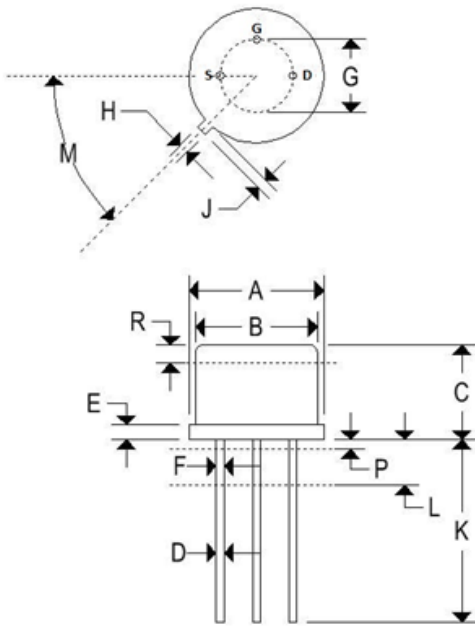
Characteristics	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Drain-Source Breakdown Voltage $V_{GS} = 0V, I_D = 1.0mA$	$V_{(BR)DSS}$	100	-	V
Gate-Source Voltage (Threshold) $V_{DS} \geq V_{GS}, I_D = 0.25mA$ $V_{DS} \geq V_{GS}, I_D = 0.25mA, T_J = +125^\circ\text{C}$ $V_{DS} \geq V_{GS}, I_D = 0.25mA, T_J = -55^\circ\text{C}$	$V_{GS(th)1}$ $V_{GS(th)2}$ $V_{GS(th)3}$	2.0 1.0 -	4.0 - 5.0	V
Gate Current $V_{GS} = \pm 20V, V_{DS} = 0V$ $V_{GS} = \pm 20V, V_{DS} = 0V, T_J = +125^\circ\text{C}$	I_{GSS1} I_{GSS2}	- -	±100 ±200	nA
Drain Current $V_{GS} = 0V, V_{DS} = 80V$	I_{DSS1}	-	25	µA
Drain Current $V_{GS} = 0V, V_{DS} = 80V, T_J = +125^\circ\text{C}$	I_{DSS2}	-	0.25	mA
Static Drain-Source On-State Resistance $V_{GS} = 10V, I_D = 5.0A$ pulsed	$r_{DS(on)1}$	-	0.18	Ω
Static Drain-Source On-State Resistance $V_{GS} = 10V, I_D = 8.0A$ pulsed	$r_{DS(on)2}$	-	0.195	Ω
Static Drain-Source On-State Resistance $T_J = 125^\circ\text{C}$ $V_{GS} = 10V, I_D = 5.0A$ pulsed	$r_{DS(on)1}$	-	0.35	Ω
Diode Forward Voltage $V_{GS} = 0V, I_D = 8.0A$ pulsed	V_{SD}	-	1.5	V

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristics	Symbol	Min	Max	Unit
DYNAMIC CHARACTERISTICS				
On-State Gate Charge $V_{GS} = 10\text{V}, I_D = 8.0\text{A}, V_{DS} = 50\text{V}$	$Q_{g(\text{on})}$	-	28.51	nC
Gate to Source Charge $V_{GS} = 10\text{V}, I_D = 8.0\text{A}, V_{DS} = 50\text{V}$	Q_g	-	6.34	nC
Gate to Drain Charge $V_{GS} = 10\text{V}, I_D = 8.0\text{A}, V_{DS} = 50\text{V}$	Q_{gd}	-	16.59	nC
SWITCHING CHARACTERISTICS				
Turn-On Delay Time $I_D = 8.0\text{A}, V_{GS} = +10\text{V}, R_G = 7.5\Omega, V_{DD} = 30\text{V}$	$t_{d(\text{on})}$	-	30	ns
Rinse Time $I_D = 8.0\text{A}, V_{GS} = +10\text{V}, R_G = 7.5\Omega, V_{DD} = 30\text{V}$	t_r	-	75	ns
Turn-off Delay Time0 $I_D = 8.0\text{A}, V_{GS} = +10\text{V}, R_G = 7.5\Omega, V_{DD} = 30\text{V}$	$t_{d(\text{off})}$	-	40	ns
Fall Time $I_D = 8.0\text{A}, V_{GS} = +10\text{V}, R_G = 7.5\Omega, V_{DD} = 30\text{V}$	t_f	-	45	ns
Diode Reverse Recovery Time $di/dt \leq 100\text{A}/\mu\text{s}, V_{DD} = \leq 50\text{V}, I_F = 8.0\text{A}$	t_{rr}	-	300	ns

MECHANICAL CHARACTERISTICS

Case:	TO-205 low-profile
Marking:	Alpha-numeric
Pin out:	See below



	TO-205 LOW PROFILE			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.350	0.370	8.890	9.400
B	0.315	0.335	8.000	8.510
C	-	0.180	-	4.57
D	0.016	0.021	0.406	0.533
E	0.009	0.125	0.2269	3.180
F	0.016	0.019	0.406	0.533
G	0.190	0.210	4.830	5.33
H	0.028	0.034	0.711	0.864
J	0.029	0.040	0.737	1.020
K	0.500	-	12.700	-
L	0.250	-	6.350	-
M	45° NOM		45° NOM	
P	-	0.050	-	1.270
Q	90° NOM		90° NOM	
R	0.100	-	2.540	-

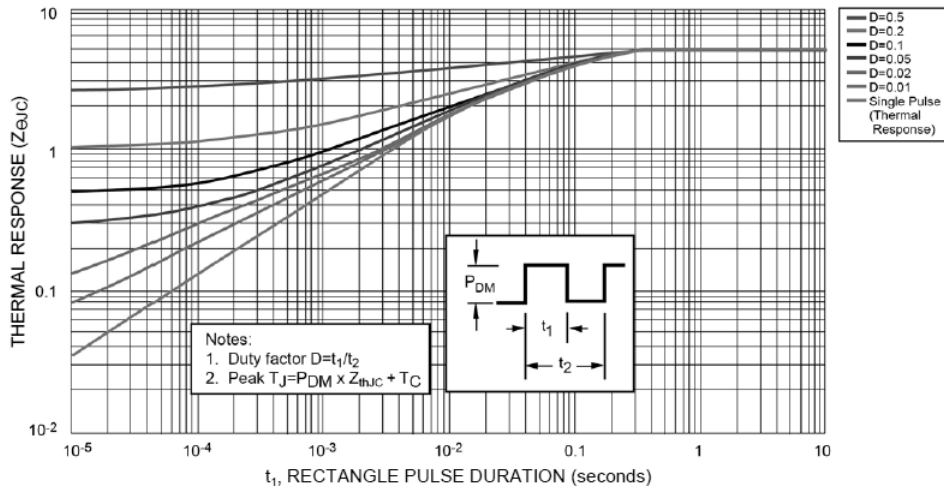


FIGURE 1 – Normalized Transient Thermal Impedance

